

FEATURES

- For surface mounted applications
- Low profile package
- Built-in strain relief
- Easy pick and place
- Superfast recovery times for high efficiency
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Glass passivated junction
- High temperature soldering: 260 C /10 seconds at terminals

MECHANICAL DATA

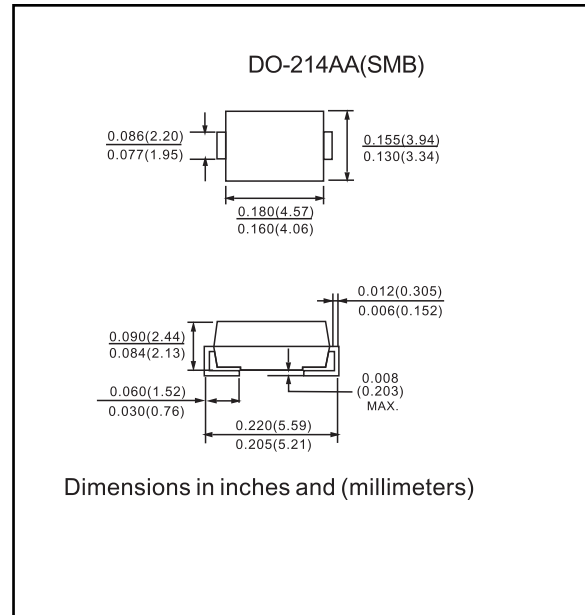
Case: JEDEC DO-214AA molded plastic

Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

Polarity: Indicated by cathode band

Standard packaging: 12mm tape (EIA-481)

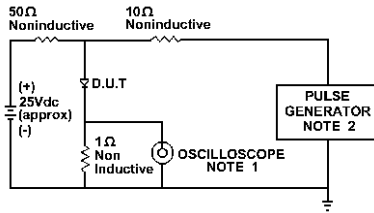
Weight: 0.003 ounce, 0.093 gram



Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Characteristic	Symbol	ER1A	ER1B	ER1C	ER1D	ER1E	ER1G	ER1J	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	50	100	150	200	300	400	600	V
Working Peak Reverse Voltage	V_{RWM}								
DC Blocking Voltage	V_R								
RMS Reverse Voltage	$V_{R(RMS)}$	35	70	105	140	210	280	420	V
Average Rectified Output Current @ $T_L = 100^{\circ}\text{C}$	I_o	1.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30							A
Forward Voltage @ $I_F = 1.0\text{A}$	V_{FM}	0.95				1.25		1.7	V
Peak Reverse Current @ $T_A = 25^{\circ}\text{C}$ At Rated DC Blocking Voltage @ $T_A = 100^{\circ}\text{C}$	I_{RM}					5.0			μA
						500			
Reverse Recovery Time (Note 1)	t_{rr}					35			nS
Typical Junction Capacitance (Note 2)	C_j					10			pF
Typical Thermal Resistance (Note 3)	$R_{\theta JL}$					34			K/W
Operating and Storage Temperature Range	T_j, T_{STG}	-65 to +150							$^{\circ}\text{C}$

Note: 1. Measured with $I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$, $I_{rr} = 0.25\text{A}$,
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.
 3. Mounted on P.C. Board with 8.0mm² land area.



NOTE:1.Rise Time = 7ns max.
Input Impedance = 1 megohm. 22pF
2.Rise Time = 10ns max.
Source Impedance = 50 Ohms

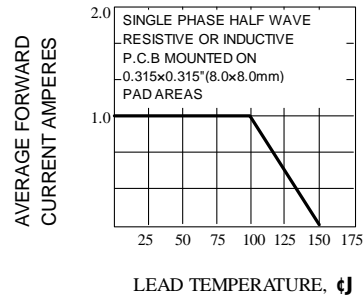
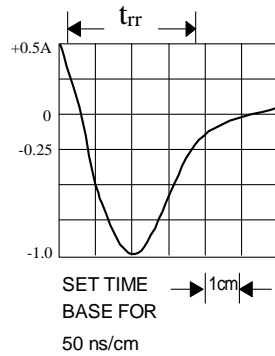


Fig. 1-REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

Fig. 2-MAXIMUM AVERAGE FORWARD CURRENT RATING

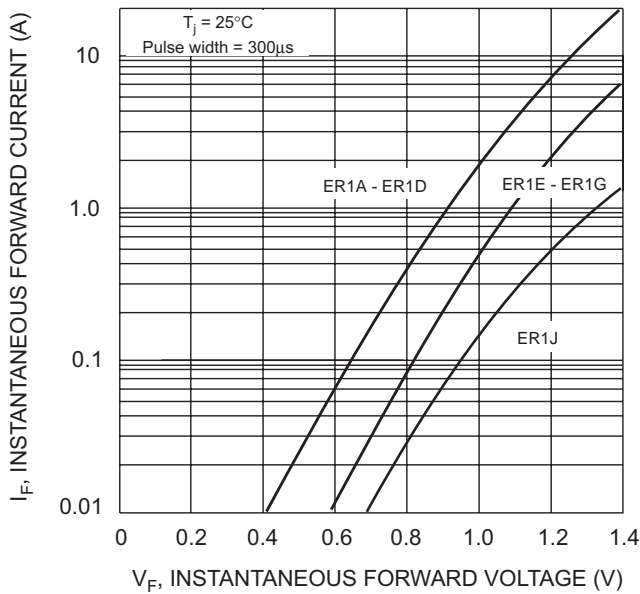


Fig.3 Typical Forward Characteristics

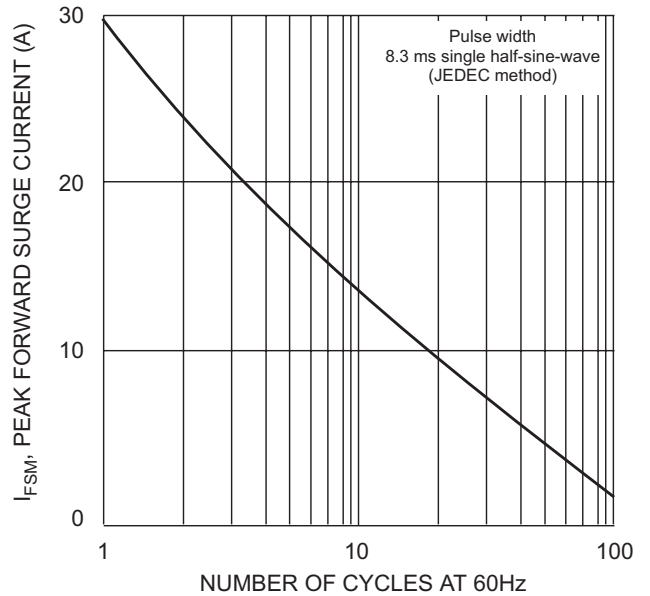


Fig.4 PEA FORWARD SURGE CURRENT

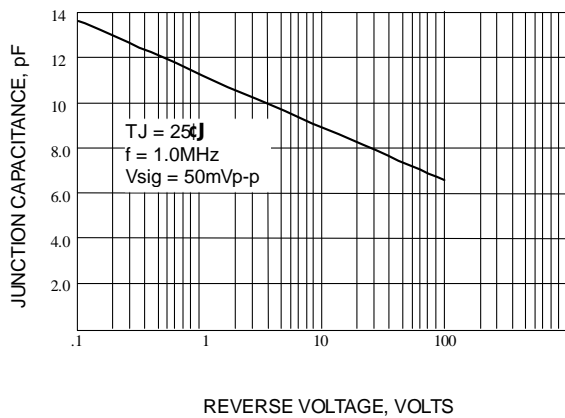


Fig. 5-TYPICAL JUNCTION CAPACITANCE